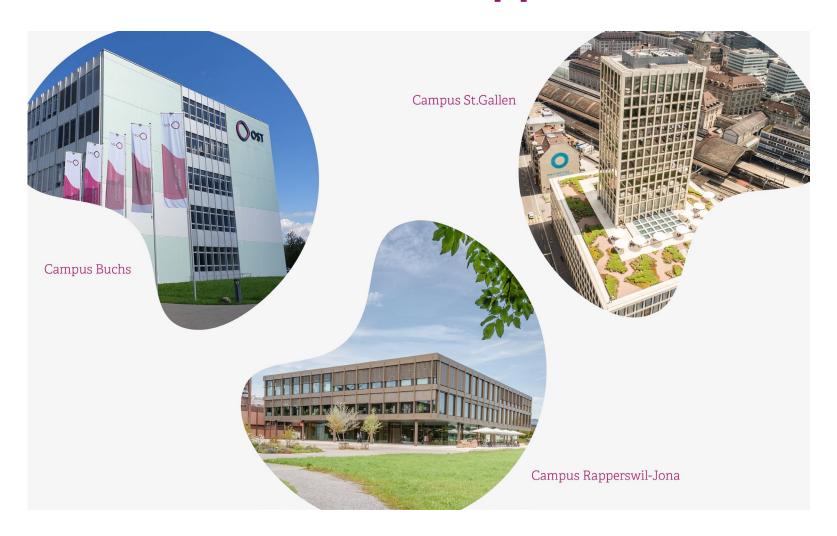






OST – Universities of applied sciences





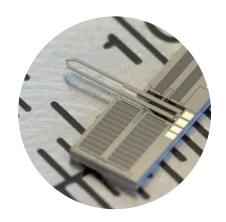


email: jens.ulmer@ost.ch





Institute for Microtechnology and Photonics (IMP)



Microtechnology

MEMS design and fabrication **Packaging Printing & Pattern Technologies**



Cleanroom

Infrastructure (620 m² ISO 5-7)

Complete 8" Processing

Pilot series



Photonics

Waveguides

Machine Vision

Laser-Processing

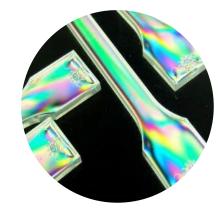


Optics



Certified coordinate measurements

Micro- and nano-topography



Materials

Surface functionalization Polymer formulation Materials testing Surface analysis





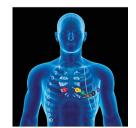
Overview where particles add functionality

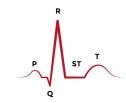
Thermal conductive adhesive

enabeling cell to pack design in BEV



Electroconductive Polymer enabeling longterm vital sign monitoring







Challenges

- Viscosity
- Sedimentation
- Interfacial adhesion

Critical parameters

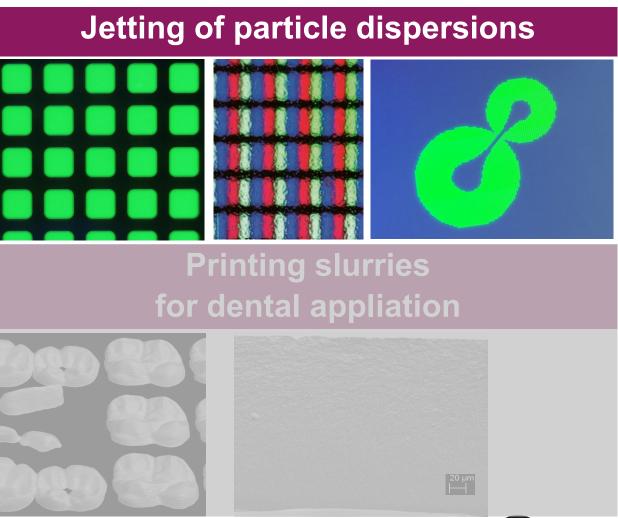
- Matrix particle interaction
- → tuning particle surface by functionalization
- Particle size
- → adjusting and controlling size distribution by wet milling
- Particle materials
- → combining different materials to improve properites





Overview where particles add functionality

Thermal conductive adhesive Highly filled, conductive TPU for medical application





45267.1-IP-EE: 2K-Gapfiller

Problem:

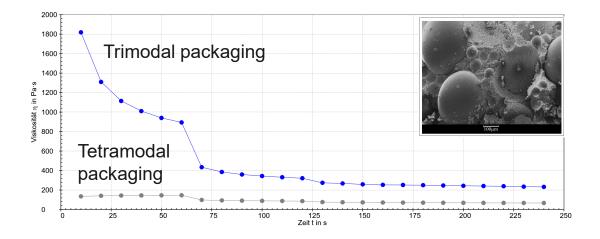
Highly filled polymer systems tend to have high viscosity

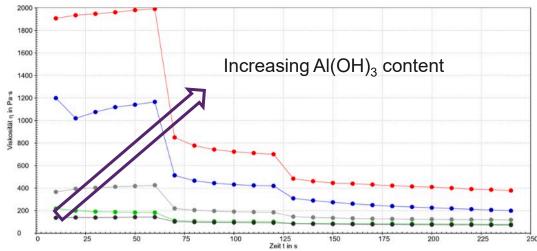
Solution:

- Optimize particle packaging to increase thermal conductivity
- Adjust surface energy to polymer matrix

Properties:

- Viscosity optimized gap filler
- Therma conductivity of 3 W/mK







32618.1-IP-ENG: Long term skin electrodes - Dryodes

Flexible core

Problem:

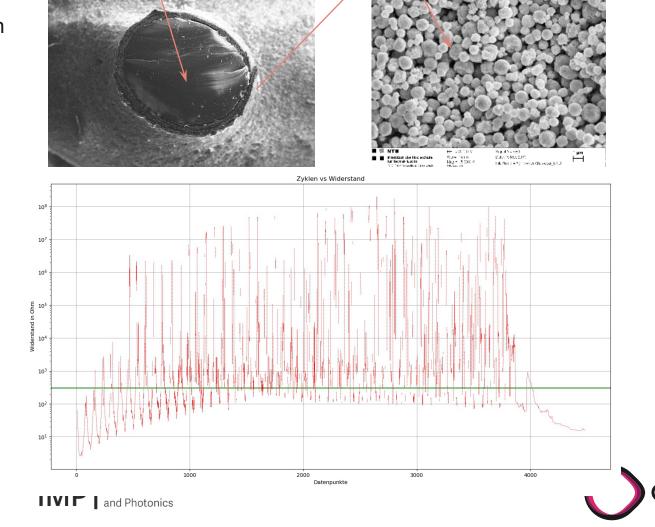
Highly filled polymers have low tensile strength

Solution:

- Flexible core: TPU
- Conductive layer: Ag Powder/Flakes in TPU

Properties:

- High conductivity at "high" tensile strain (20%)
- Conductivity recovers after high strain
- Mechanical properties similar to base TPU



Conductive layer

Avantama

Problem:

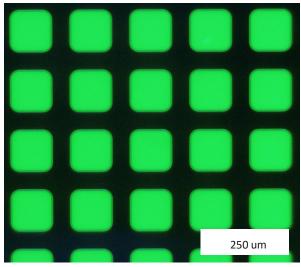
Jetting of highly filled suspensions

Solution:

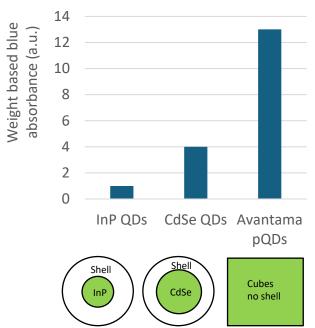
- Adapting particle size and surface tension
- Modifing matrix chemistry
- Ballancing rheological additives

Properties:

Jetting supension with 30 wt% filling



Green pQD ink-jet ink printed into black banks (130µm pixel size)

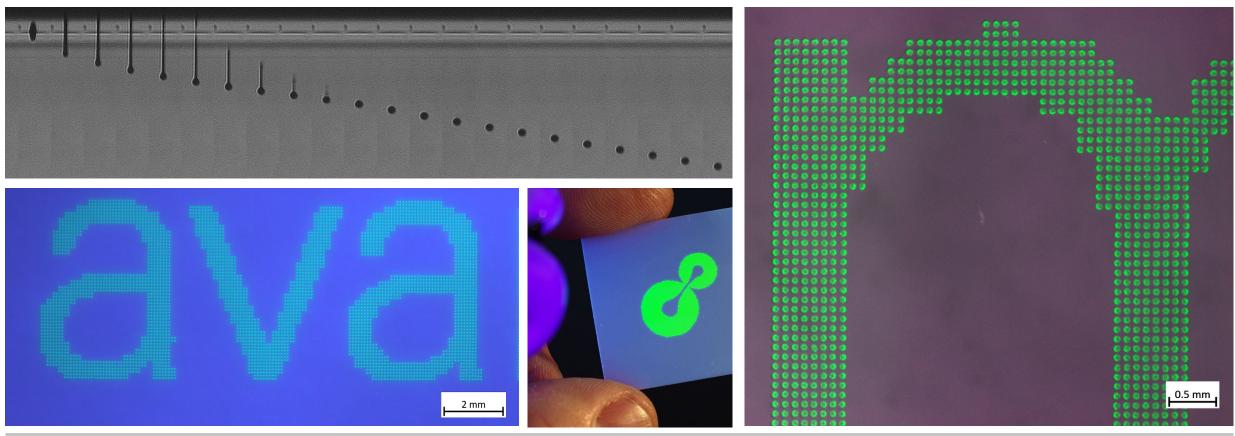








Jetting & Printing of pQD-Inks



Printed demonstrator exhibited at world's leading display show (SID Display Week '24)

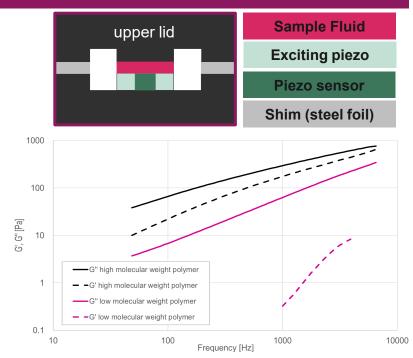




Rheological Characterisation Techniques at IMP

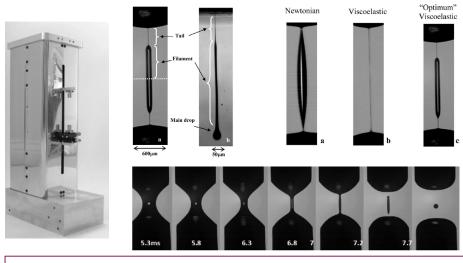
TriPAV (High Frequency Rheometer)





- Complex rheology analysis (oscillatory, sinus signal): Studying jet-ability of inks
- TriPAV printhead mode standard square waveform: Characterisation of ink damping behaviour

TriMaster (Filament Stretch Rheometer)



- TriMaster is a capillary breakup extensional rheometer to measure the extensional and filament stretching behaviour of complex fluids colloids, polymer solutions, paints inks, food, consumer products and melts.
- The Trimaster investigate the elongation properties of viscoelastic fluids by stretching a small amount of fluid attached between two identical pistons.



